

## 1025. Technology

1. "Technology" according to the General Technology Note for the "development" of equipment or "software" controlled by 1021., 1022. or 1024.
2. "Technology" according to the General Technology Note for the "production" of equipment controlled by 1021. or 1022.
3. Other technology, as follows:
  - a. "Technology" for the "development" of interactive graphics as an integrated part in "numerical control" units for preparation or modification of part programmes;
  - b. "Technology" for metal-working manufacturing processes, as follows:
    1. Technology for the design of tools, dies or fixtures specially designed for the following processes:
      - a. "Superplastic forming";
      - b. "Diffusion bonding"; **or**
      - c. "Direct-acting hydraulic pressing";
    2. Technical data consisting of process methods or parameters as listed below used to control:
      - a. "Superplastic forming" of aluminum alloys, titanium alloys or "superalloys":
        1. Surface preparation;
        2. Strain rate;
        3. Temperature;
        4. Pressure;
      - b. "Diffusion bonding" of "superalloys" or titanium alloys:
        1. Surface preparation;
        2. Temperature;
        3. Pressure;
      - c. "Direct-acting hydraulic pressing" of aluminum alloys or titanium alloys:
        1. Pressure;
        2. Cycle time;
      - d. "Hot isostatic densification" of titanium alloys, aluminum alloys or "superalloys":
        1. Temperature;
        2. Pressure;
        3. Cycle time;
  - c. "Technology" for the "development" or "production" of hydraulic stretch-forming machines and dies therefore, for the manufacture of airframe structures;
  - d. "Technology" for the "development" of generators of machine tool instructions (e.g., part programmes) from design data residing inside "numerical control" units;
  - e. "Technology" for the "development" of integration "software" for incorporation of expert systems for advanced decision support of shop floor operations into "numerical control" units;
  - f. "Technology" for the application of inorganic overlay coatings or inorganic surface modification coatings (specified in column 3 of the following Table) to non-electronic substrates (specified in column 2 of the following table), by processes specified in column 1 of the following table and defined in the Technical Note.

**N.B.:**

*This Table should be read to control the technology of a particular 'Coating Process' only when the 'Resultant Coating' in column 3 is in a paragraph directly across from the relevant 'Substrate' under column 2. For example, Chemical Vapour Deposition (CVD) coating process*

*technical data are controlled for the application of 'silicides' to 'Carbon-carbon, Ceramic and Metal "matrix" "composites" substrates, but are not controlled for the application of 'silicides' to 'Cemented tungsten carbide (16), Silicon carbide (18)' substrates. In the second case, the 'Resultant Coating' is not listed in the paragraph under column 3 directly across from the paragraph under column 2 listing 'Cemented tungsten carbide (16), Silicon carbide (18)'.*